

a board, wherein the external connecting terminal is joined to a surface of the board and projects therefrom on a side opposite the semiconductor chip with respect to the board.

7. (Twice Amended) A semiconductor device, comprising:
a board;

a semiconductor chip joined to the board in the state where its active surface is opposite to the board and its inactive surface which is a surface on the opposite side of the active surface is exposed; and

an external connecting terminal electrically connected to the active surface of the semiconductor chip and projecting therefrom, wherein the external connecting terminal is joined to a surface of the board that is facing away from the semiconductor chip, the external connecting terminal projects from the surface.

REMARKS

Claims 1-17 are pending in the application. By this Amendment, claims 1 and 7 are amended. Claims 10-17 stand withdrawn from consideration.

Entry of the Amendment is proper under 37 C.F.R. §1.116 because the Amendment: a) places the application in condition for allowance for the reasons discussed herein; b) does not raise any new issue requiring further search and/or consideration because the Amendment's amplified issues previously discussed throughout prosecution; c) does not present any additional claims without canceling a corresponding number of finally rejected claims; and d) places the application in better form for appeal, should an Appeal be necessary. The Amendment is necessary and was not earlier presented because it is made in response to arguments raised in the final rejection. The Amendments to the subject claims do not incorporate any new subject matter into the claims. Thus, entry of the Amendment is respectfully requested.

Claims 1-9 are rejected under 35 U.S.C. 103(a) as anticipated by Lum (U.S. Patent No. 5,959,462). The rejection is respectfully traversed.

Lum teaches a test structure for enabling burn-in testing on an entire semiconductor wafer. As shown in the Figs. 4-7, Lum teaches a semiconductor device 10 that includes a semiconductor chip 28, a protective resin 36 and an external connecting terminal.

Claim 1 is directed to a semiconductor device that a semiconductor chip, a protective resin, an external connecting terminal and a board. The protective resin covers a sidewall of the semiconductor chip and has a surface formed so as to be flush with an inactive surface of the semiconductor chip which is a surface on the opposite side of an active surface of the semiconductor chip. The external connecting terminal is electrically connected to the active surface of the semiconductor chip and projects therefrom. Claim 1 recites that the external connecting terminal is joined to a surface of the board and projects therefrom on a side opposite the semiconductor chip with respect to the board.

It is respectfully submitted that the rejection is improper because the applied art fails to teach each element of claim 1. Specifically, the applied art fails to teach an external connecting terminal joined to a surface of a board and projects therefrom on a side opposite a semiconductor chip with respect to the board. Thus, it is respectfully submitted that claim 1 is allowable over the applied art.

Claim 7 is directed to a semiconductor device that includes a board, a semiconductor chip and an external connecting terminal. The semiconductor chip is joined to the board in the state where its active surface is opposite to the board and its inactive surface which is a surface on the opposite side of the active surface is exposed. The external connecting terminal is electrically connected to the active surface of the semiconductor chip and projects therefrom. Claim 7 recites that the external connecting terminal is joined to a surface of the board that is facing away from the semiconductor chip and the external connecting terminal projects from the surface.

It is respectfully submitted that the rejection is improper because the applied art fails to teach each element of claim 7. Specifically, the applied art fails to teach an external connecting terminal joined to a surface of the board that faces away from the

semiconductor chip with an external connecting terminal projecting from the surface. As a result, it is respectfully submitted that claim 7 is allowable over the applied art.

Claims 2-6 depend from claim 1 and include all of the features of claim 1. Claims 8 and 9 depend from claim 7 and include all of the features of claim 7. It is respectfully submitted that the dependent claims are allowable at least for the reasons the independent claims are allowable as well as for the features they recite.

Withdrawal of the rejection is respectfully requested.

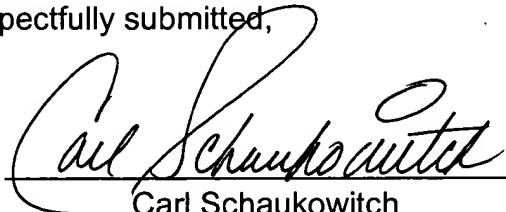
In view of the foregoing, reconsideration of the application and allowance of the pending claims are respectfully requested. Should the Examiner believe anything further is desirable in order to place the application in even better condition for allowance, the Examiner is invited to contact Applicants' representative at the telephone number listed below.

Should additional fees be necessary in connection with the filing of this paper or if a Petition for Extension of Time is required for timely acceptance of the same, the Commissioner is hereby authorized to charge Deposit Account No. 18-0013 for any such fees and Applicant(s) hereby petition for such extension of time.

Respectfully submitted,

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Enclosure(s): Marked-Up Version of Amended Claims
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MARKED-UP VERSION OF AMENDED CLAIMS

1. (Twice Amended) A semiconductor device, comprising:
a semiconductor chip;
protective resin covering a sidewall of the semiconductor chip and having
a surface formed so as to be flush with an inactive surface of the semiconductor chip
which is a surface on the opposite side of an active surface of the semiconductor chip;
and
an external connecting terminal electrically connected to the active
surface of the semiconductor chip and projecting therefrom; and
a board, wherein the external connecting terminal is joined to a surface of
the board and projects therefrom on a side opposite the semiconductor chip with
respect to the board.

7. (Twice Amended) A semiconductor device, comprising:
a board;
a semiconductor chip joined to the board in the state where its active
surface is opposite to the board and its inactive surface which is a surface on the
opposite side of the active surface is exposed; and
an external connecting terminal electrically connected to the active
surface of the semiconductor chip and projecting therefrom, wherein the external
connecting terminal is joined to a surface of the board that is facing away from the
semiconductor chip, the external connecting terminal projects from the surface.